



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No. 4981
Hiroshi TAKANASHI et al. : Docket No. 2000-1749
Serial No. 09/739,750 : Group Art Unit 1752
Filed December 20, 2000 : Examiner S. Lee

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RESPONSE TO FINAL REJECTION

Assistant Commissioner for Patents,
Washington, D.C.

RESPONSE UNDER 37. CFR 1.116
EXPEDITED PROCEDURE
PENDING GROUP 1752

Sir:

In response to the Official Action dated June 19, 2002, the period for response having been extended for two months by the attached petition, please amend the present application as follows:

IN THE SPECIFICATION

Please rewrite paragraph [0056] as follows:

[0056] EXAMPLES 1 - 17:

(i) Preparation of water-soluble photosensitive resin compositions 1-17:

In 200 parts by weight of water was dissolved 200 parts by weight of polyvinyl alcohol (degree of saponification: 70%, degree of polymerization: 500) as component (A), and then 70 parts by weight of polyethylene glycol diacrylate as component (B), 4 parts by weight of benzyldimethyl ketal as component (C), 0.1 part by weight of methylhydroquinone as component (D), and X parts by weight (X: addition amount indicated in Table I below) of p-toluenesulfonamide were added as component (E) to the solution to prepare water-soluble photosensitive resin compositions 1 - 17.

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